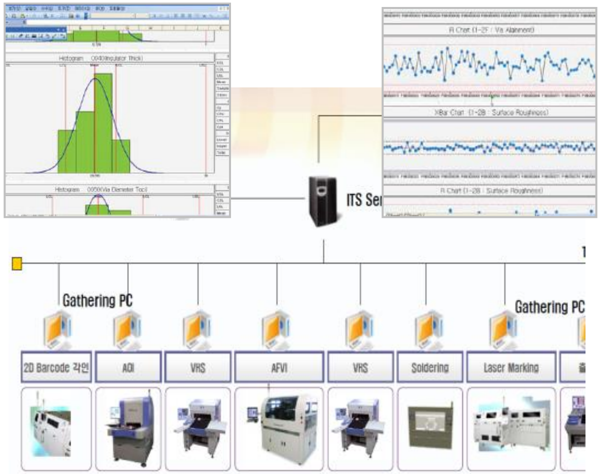
Facility strengths

Item	Feature	
Dust Control	◆ All Factory Clean Control - Image / PSR : 1,000 Class - Lay-up / AOI / BBT / Final Inspection : 10,000 Class	
Product Handling	◆ Full Auto Line - Full auto Lay-up - Auto L/Unloading of Cu Plating and Ni/Au Plating process - Auto Sorter (Including Air Cleaner) ◆ Non contact Line - MSAP Developer / PSR Developer	

Facility strengths

Item	Feature	
Quick Turn	◆ Film-less exposure M/C (Art work film-free) - Image LDI / PSR UV-DI ◆ All Process In-house - None Outsourcing	
DATA Control	◆ ITS (Information Tracking System) - Products Tracking (Panel / Strip level) - X-out Auto Tracking & Non-scratch (AOI, AFVI) ◆ SPC System - SPC Control both of X and Y factor in every process	

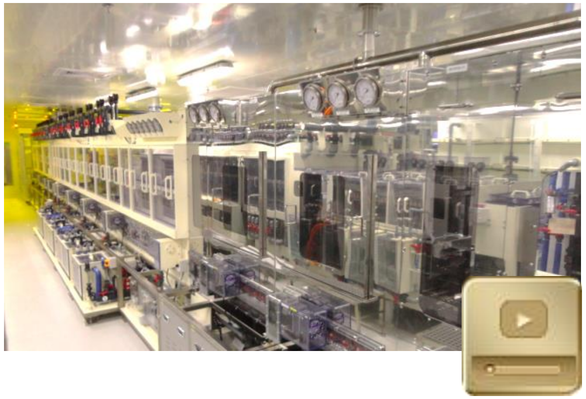
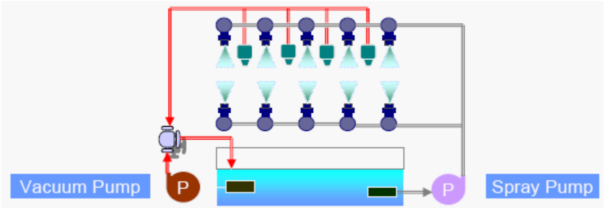
Facility strengths

Item	Feature	
Lamination Auto Layup	◆ Full Auto Lay-up system - High quality assurance Auto thick. measurement : 15pt/pnl ◆ High productivity - over 4pnls/min	
Continuous Vertical E'lectro Cu Plating	◆ Dedicated thin panel plating - 0.04mmT core with 2/2um Cu foil ◆ Dedicated filled via plating - Dimple ≤ 5um(FC) / 168ea Rectifier ◆ High quality plating system - Covariance ≤ 5%, Range ≤ 5um with 25um panel plating	

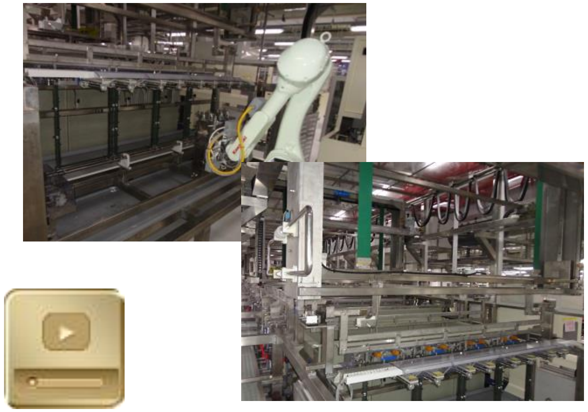
Facility strengths

Item	Feature	
Image LDI	◆ Non contact - No need film : Reducing lead-time and Decreasing running cost - Less scratch, Dent, Foreign material ◆ High resolution - L/S=15/15㎛ ◆ High alignment accuracy - under ±10um	
Vacuum-laminator	◆ All automatic system - Auto cut Pre-tack + Vacuum laminator ◆ Thin panel capability - 0.04mmT core with 2/2um Cu foil ◆ Adoptable all material - DF/ABF/DFSR ◆ for PSR flatten - PSR flatness: ≤3um	

Facility strengths

Item	Feature	
MSAP & PSR Developer (Contact free)	◆ **Non contact** **- Increasing quality and capability** **- Less D/F damage, Less Scratch, Less Foreign material** ◆ **Thin panel capability** **- 0.04mmT**	
DES Vacuum Etching	◆ **Vacuum etching system** **- Improvement of etching efficiency L/S=25/25㎛ (by subtractive method)**	 

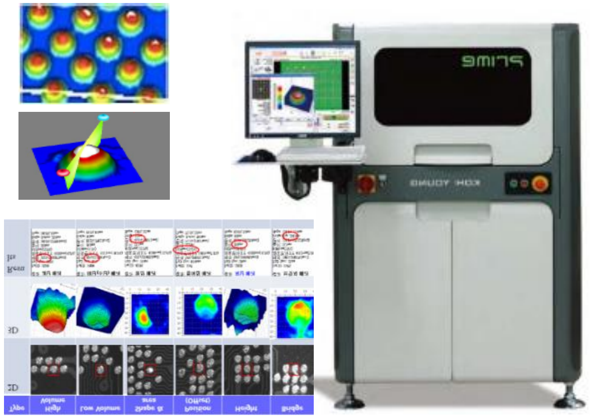
Facility strengths

Item	Feature	
PSR UV-DI	◆ Non contact - No need film : Reducing lead-time and Decreasing running cost - Less scratch, Dent, Foreign material ◆ High resolution system - SR Opening min.50um ◆ High alignment accuracy - under ±15um	
Au plating	◆ Full Automation - All moving part adopted 'Raydent coating' to prevent corrosion - Auto L/Unloading ◆ Excellent thickness uniformity - Cpk≥1.33	

Facility strengths

Item	Feature	
SOP Solder printer	◆ Adopting ‘Pump head’ - Increasing solderpaste transferring efficiency - min. bump pitch 140um	
Coining machine	◆ High bump quality by adopting ‘Ceramic punch’ - Less dent, scratch, chip off ◆ High alignment accuracy - Adopting CCD, alignment accuracy ±0.1mm	

Facility strengths

Item	Feature	
SOP X-Ray Void inspection	◆ Semi-automatic bump void inspection - Void monitoring and management after deflux ◆ Fine resolution - 100nm	
SOP 3D-SPI	◆ Quality assurance - First article check after Solderprint and Coining ◆ High accuracy - 4way projection system : Height 1um / Volume 3% ◆ Inspection capability - min. bump dia. 60um / pitch 120um	

Thank you for attention!